

General Description:

FRED from GL utilizes advanced processing techniques to achieve ultrafast recovery times and higher forward current. Its soft recovery characteristics and high reliability suit for wide industrial applications.

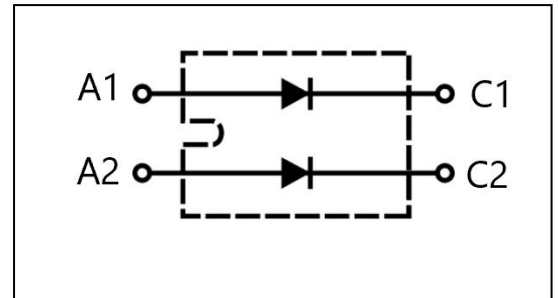
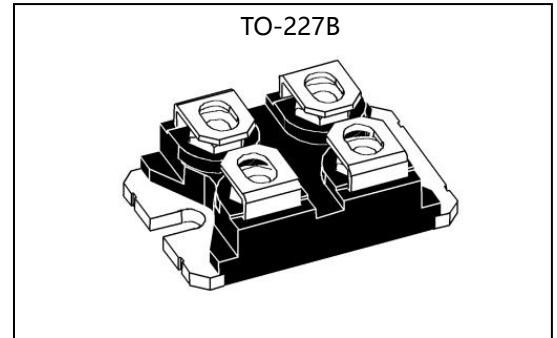
V_{RRM}	1200	V
I_{FAVM}	2×100	A
$P_D(T_C=25^\circ\text{C})$	250	W
t_{rr}	40	nS

Features:

- Ultrafast Recovery Time
- Soft Recovery Characteristics
- Low Recovery Loss
- Low Forward Voltage
- High Surge Current Capability
- Low Leakage Current

Applications:

- Freewheeling, Snubber, Clamp
- Inversion Welder
- PFC
- Plating Power Supply
- Ultrasonic Cleaner and Welder
- Converter & Chopper
- UPS



Absolute ($T_C=25^\circ\text{C}$ unless otherwise specified) :

Symbol	Parameter	Test conditions	Rating	Units
V_R	Maximum D.C. Reverse Voltage		1200	V
V_{RRM}	Maximum Repetitive Reverse Voltage		1200	V
$I_{F(AV)}$	Average Forward Current	$T_C=110^\circ\text{C}$, Per Diode	100	A
		$T_C=110^\circ\text{C}$, Per Package	182	A
$I_{F(RMS)}$	RMS Forward Current	$T_C=110^\circ\text{C}$, Per Diode	150	A
I_{FSM}	Non-Repetitive Surge Forward Current	$T_J=45^\circ\text{C}$, $t=10\text{ms}$, 50Hz, Sine	900	A
P_D	Power Dissipation		250	W
T_J	Junction Temperature		-40 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-40 to +150	$^\circ\text{C}$
Torque	Module-to-Sink	Recommended (M4)	1.5	Nm
$R_{\theta JC}$	Thermal Resistance	Junction-to-Case	0.5	$^\circ\text{C} / \text{W}$



GRFN200F1200A

GL Silicon Fast Recovery Epitaxial Diode

Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified) :

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I_{RM}	Reverse Leakage Current	$V_R = 1200\text{V}$	--	--	3	mA
		$V_R = 960\text{V}, T_J = 125^\circ\text{C}$	--	--	15	mA
V_F	Forward Voltage	$I_F = 100\text{A}$	--	--	2.2	V
		$I_F = 200\text{A}$	--	--	2.5	V
		$I_F = 100\text{A}, T_J = 150^\circ\text{C}$	--	--	1.8	V
		$I_F = 200\text{A}, T_J = 150^\circ\text{C}$	--	--	2.3	V
t_{rr}	Reverse Recovery Time	$I_F = 1\text{A}, V_R = 30\text{V}, di_F/dt = -400\text{A}/\mu\text{s}$	--	40	--	ns
t_{rr}	Reverse Recovery Time	$I_F = 100\text{A}, V_R = 600\text{V},$ $di_F/dt = -600\text{A}/\mu\text{s}$	--	150	--	ns
		$I_F = 100\text{A}, V_R = 600\text{V},$ $di_F/dt = -600\text{A}/\mu\text{s}, T_J = 125^\circ\text{C}$	--	255	--	ns
I_{RRM}	Max. Reverse Recovery Current	$I_F = 100\text{A}, V_R = 600\text{V},$ $di_F/dt = -600\text{A}/\mu\text{s}$	--	38	--	A
		$I_F = 100\text{A}, V_R = 600\text{V},$ $di_F/dt = -600\text{A}/\mu\text{s}, T_J = 125^\circ\text{C}$	--	52	--	A

Characteristics Curve:

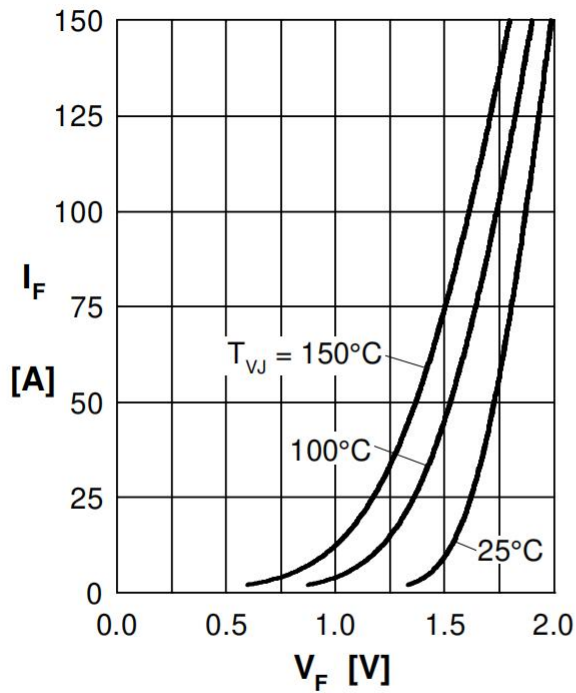


Fig. 1 Forward current I_F versus V_F

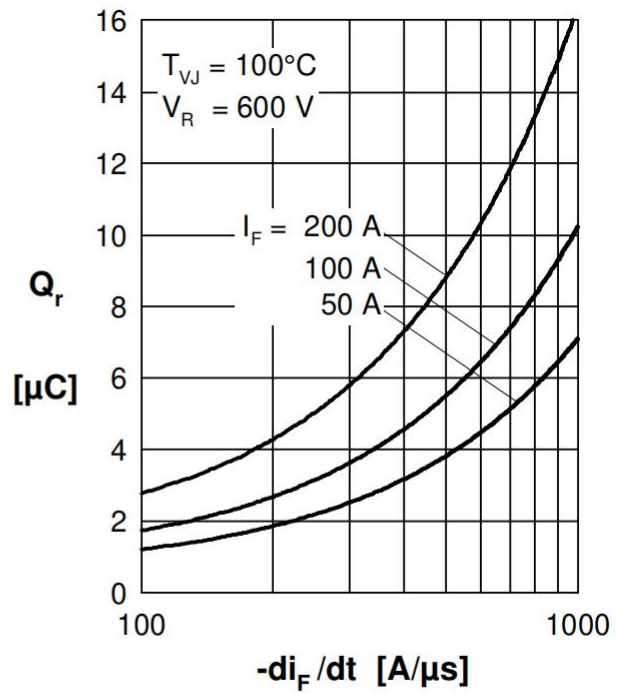


Fig. 2 Typ. reverse recov. charge Q_{rr} versus $-di_F/dt$

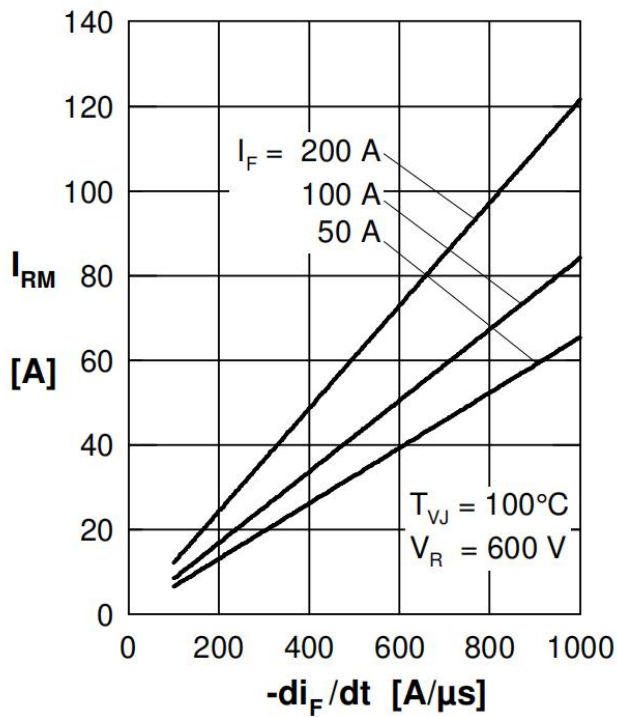


Fig. 3 Typ. peak reverse current I_{rr} versus $-di_F/dt$

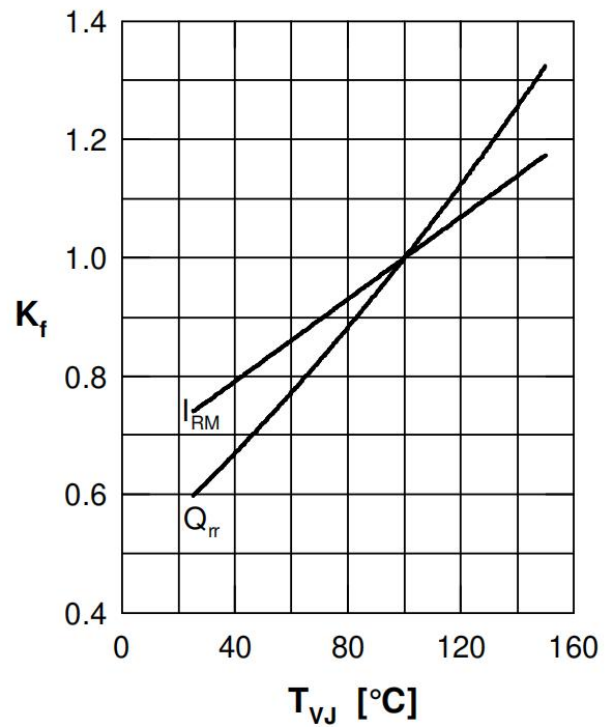


Fig. 4 Dyn. parameters Q_r , I_{RM} versus T_{VJ}

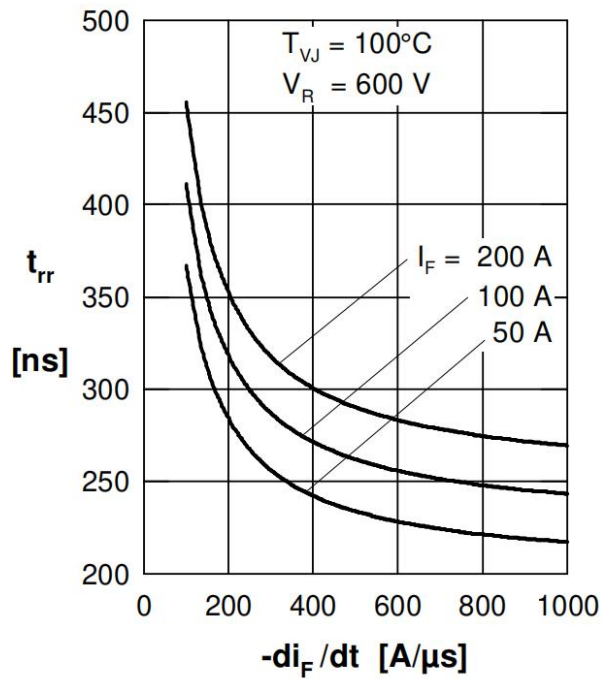


Fig. 5 Typ. recovery time t_{rr} versus $-di_F/dt$

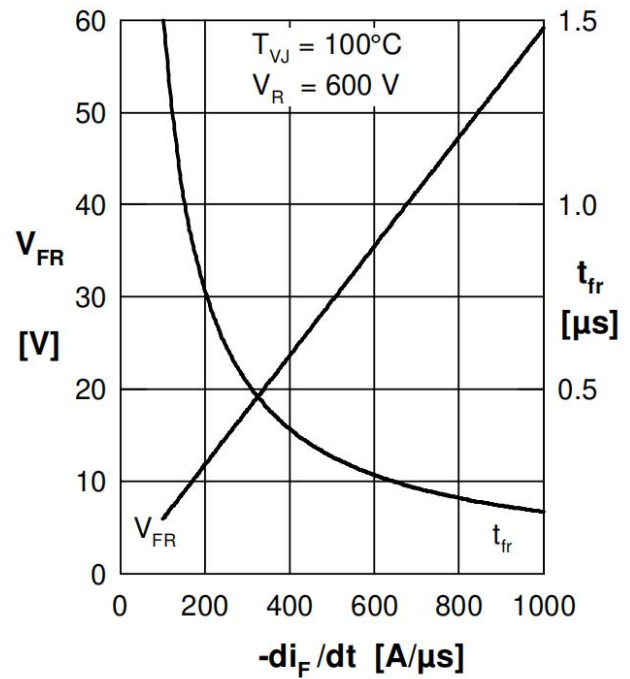


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt

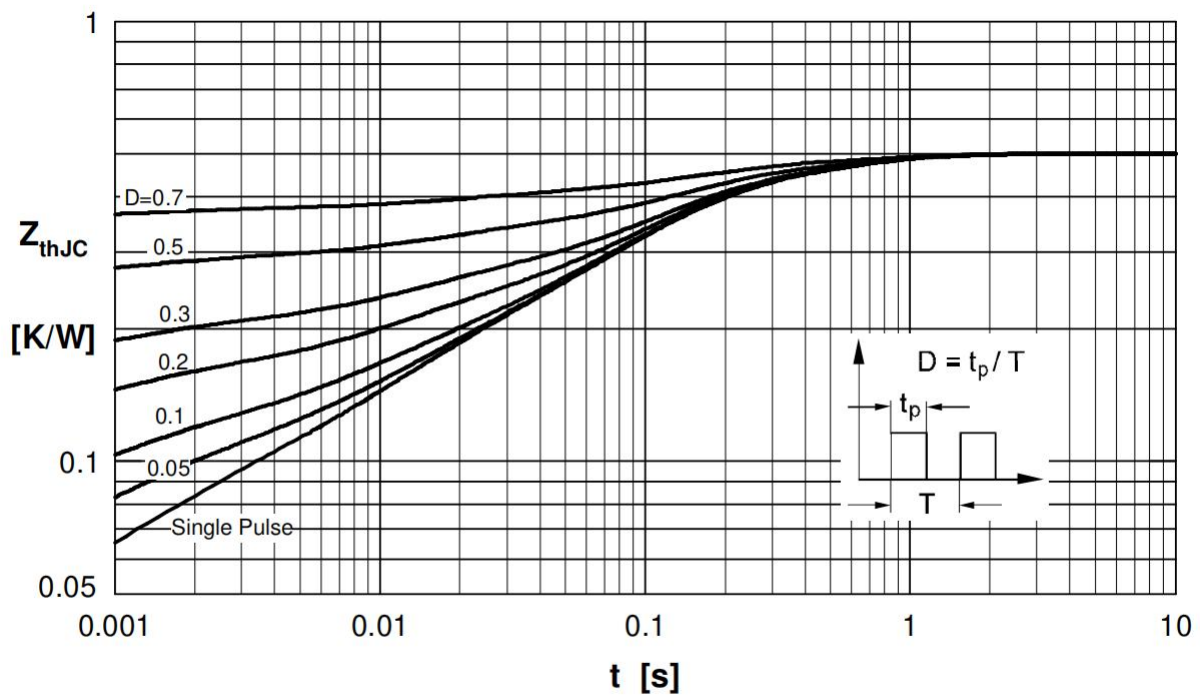


Fig. 7 Transient thermal impedance junction to case